

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV

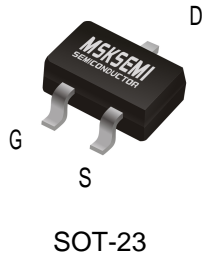


GDT



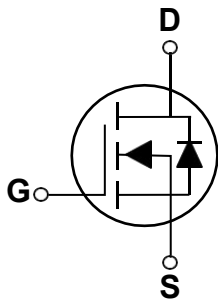
PLED

Product data sheet



**Features**

- 30V, 0.25A,  $R_{DS(ON)} = 1.5\Omega @ V_{GS}=4V$
- Improved  $dv/dt$  capability
- Fast switching
- Green Device Available



**Applications**

- Motor Drive
- Power Tools
- LED Lighting

|       |       |       |
|-------|-------|-------|
| BVDSS | RDSON | ID    |
| 30V   | 1.5Ω  | 0.25A |

**Absolute Maximum Ratings**  $T_c=25^\circ\text{C}$  unless otherwise noted

| Symbol    | Parameter  | Rating     | Units               |
|-----------|--|------------|---------------------|
| $V_{DS}$  | Drain-Source Voltage                                   | 30         | V                   |
| $V_{GS}$  | Gate-Source Voltage                                    | $\pm 16$   | V                   |
| $I_D$     | Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )  | 0.25       | A                   |
|           | Drain Current – Continuous ( $T_c=100^\circ\text{C}$ ) | 0.1        | A                   |
| $I_{DM}$  | Drain Current – Pulsed <sup>1</sup>                    | 1.0        | A                   |
| $P_D$     | Power Dissipation ( $T_c=25^\circ\text{C}$ )           | 0.35       | W                   |
|           | Power Dissipation – Derate above $25^\circ\text{C}$    | 0.003      | W/ $^\circ\text{C}$ |
| $T_{STG}$ | Storage Temperature Range                              | -50 to 150 | $^\circ\text{C}$    |
| $T_J$     | Operating Junction Temperature Range                   | -50 to 150 | $^\circ\text{C}$    |

**Thermal Characteristics**

| Symbol          | Parameter                              | Typ. | Max. | Unit               |
|-----------------|--|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | ---  | 357  | $^\circ\text{C/W}$ |

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

| Symbol                              | Parameter                                 | Conditions   | Min. | Typ. | Max. | Unit |
|-------------------------------------|---|--|------|------|------|------|
| BV <sub>DSS</sub>                   | Drain-Source Breakdown Voltage            | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA                       | 30   | ---  | ---  | V    |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | BV <sub>DSS</sub> Temperature Coefficient | Reference to 25°C, I <sub>D</sub> =1mA                           | ---  | 0.04 | ---  | V/°C |
| I <sub>DSS</sub>                    | Drain-Source Leakage Current              | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C  | ---  | ---  | 1    | uA   |
|                                     |   | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C | ---  | ---  | 100  | uA   |
| I <sub>GSS</sub>                    | Gate-Source Leakage Current               | V <sub>GS</sub> =±16V, V <sub>DS</sub> =0V                       | ---  | ---  | ±5   | uA   |

**On Characteristics**

|                      |   |  |     |      |     |       |
|----------------------|---|--|-----|------|-----|-------|
| R <sub>DS(ON)</sub>  | Static Drain-Source On-Resistance           | V <sub>GS</sub> =4V, I <sub>D</sub> =0.2A                | --- | 1.5  | 3.5 | Ω     |
| V <sub>GS(th)</sub>  | Gate Threshold Voltage                      | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA | 0.8 | 1.1  | 1.6 | V     |
| ΔV <sub>GS(th)</sub> | V <sub>GS(th)</sub> Temperature Coefficient |  | --- | -4   | --- | mV/°C |
| g <sub>fs</sub>      | Forward Transconductance                    | V <sub>DS</sub> =10V, I <sub>D</sub> =0.1A               | --- | 0.24 | --- | S     |

**Dynamic and switching Characteristics**

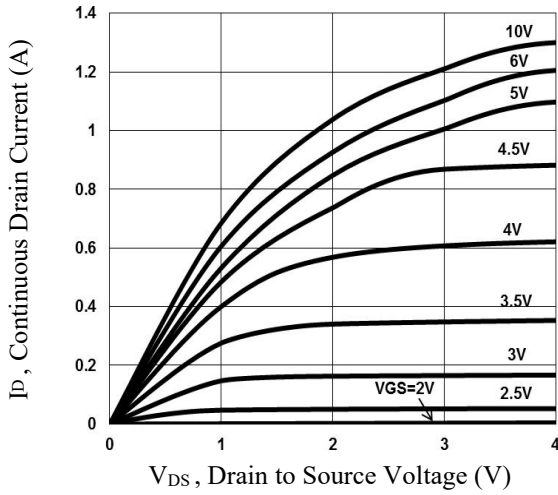
|                     |                                     |  |     |      |     |    |
|---------------------|-------------------------------------|--|-----|------|-----|----|
| Q <sub>g</sub>      | Total Gate Charge <sup>2, 3</sup>   | V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =0.2A                       | --- | 1.1  | --- | nC |
| Q <sub>gs</sub>     | Gate-Source Charge <sup>2, 3</sup>  |  | --- | 0.1  | --- |    |
| Q <sub>gd</sub>     | Gate-Drain Charge <sup>2, 3</sup>   |  | --- | 0.23 | --- |    |
| T <sub>d(on)</sub>  | Turn-On Delay Time <sup>2, 3</sup>  | V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω<br>I <sub>D</sub> =0.2A | --- | 3    | --- | ns |
| T <sub>r</sub>      | Rise Time <sup>2, 3</sup>           |  | --- | 5    | --- |    |
| T <sub>d(off)</sub> | Turn-Off Delay Time <sup>2, 3</sup> |  | --- | 14   | --- |    |
| T <sub>f</sub>      | Fall Time <sup>2, 3</sup>           |  | --- | 9    | --- |    |
| C <sub>iss</sub>    | Input Capacitance                   | V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1MHz                                      | --- | 30.6 | --- | pF |
| C <sub>oss</sub>    | Output Capacitance                  |  | --- | 5.5  | --- |    |
| C <sub>rss</sub>    | Reverse Transfer Capacitance        |  | --- | 4    | --- |    |

**Drain-Source Diode Characteristics and Maximum Ratings**

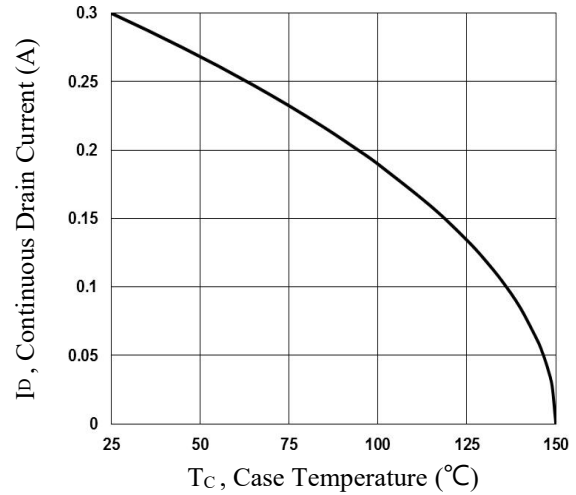
| Symbol          | Parameter                            | Conditions  | Min. | Typ. | Max. | Unit |
|-----------------|--------------------------------------|---|------|------|------|------|
| I <sub>S</sub>  | Continuous Source Current            | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current               | ---  | ---  | 0.25 | A    |
| I <sub>SM</sub> | Pulsed Source Current                |   | ---  | ---  | 0.5  | A    |
| V <sub>SD</sub> | Diode Forward Voltage                | V <sub>GS</sub> =0V, I <sub>S</sub> =0.2A, T <sub>J</sub> =25°C | ---  | ---  | 1.4  | V    |
| t <sub>rr</sub> | Reverse Recovery Time <sup>2</sup>   | V <sub>GS</sub> =30V, I <sub>S</sub> =0.2A, dI/dt=100A/μs       | ---  | ---  | ---  | ns   |
| Q <sub>rr</sub> | Reverse Recovery Charge <sup>2</sup> | T <sub>J</sub> =25°C  | ---  | ---  | ---  | nC   |

Note :

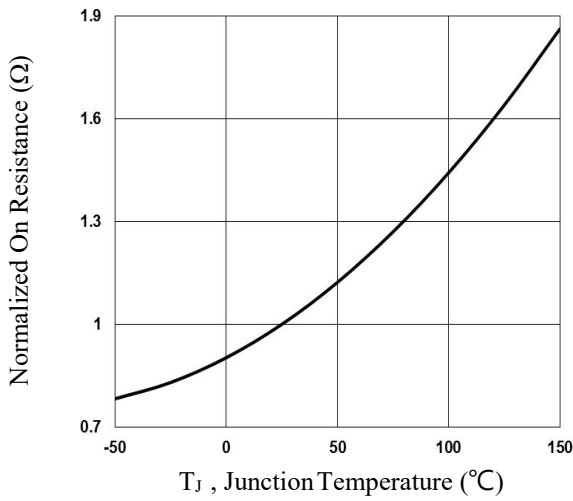
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=1mH, I<sub>AS</sub>=7A, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



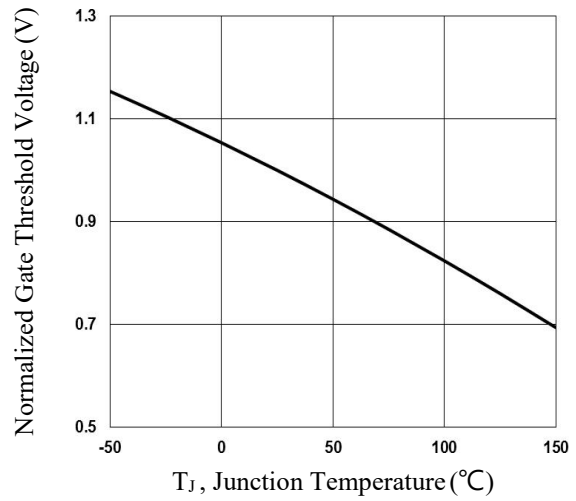
**Fig.1 Output Characteristics**



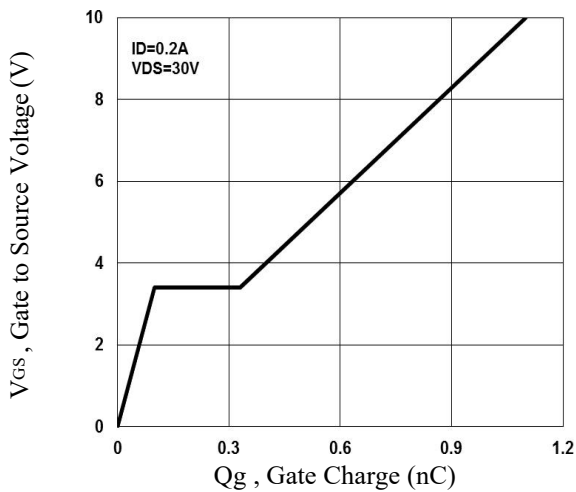
**Fig.2 Continuous Drain Current vs.  $T_c$**



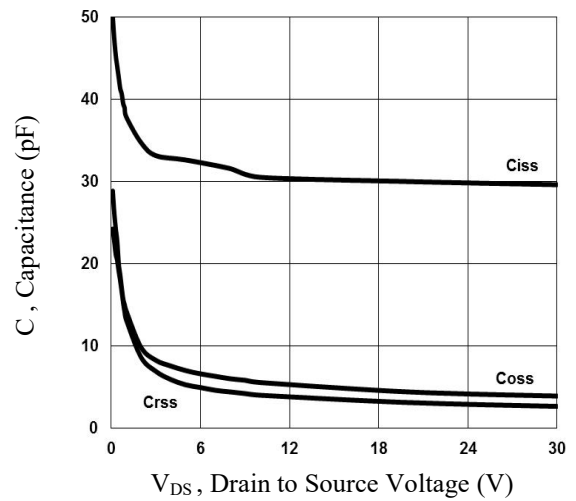
**Fig.3 Normalized  $R_{DS(on)}$  vs.  $T_J$**



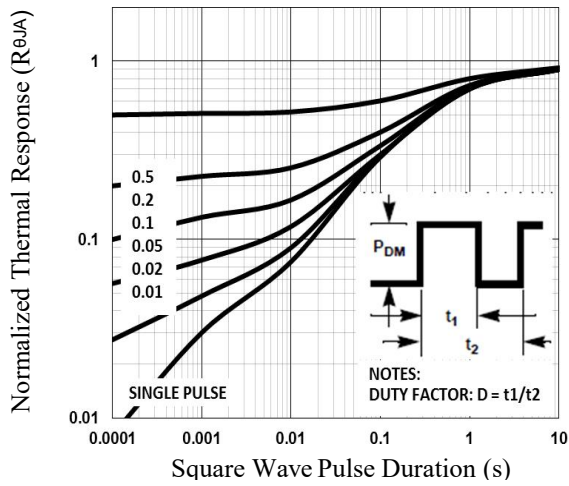
**Fig.4 Normalized  $V_{th}$  vs.  $T_J$**



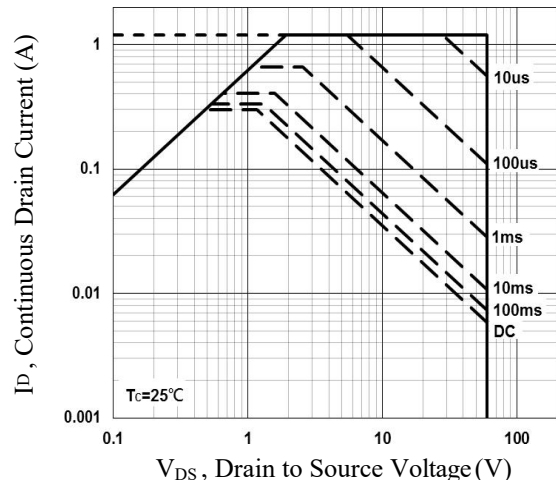
**Fig.5 Gate Charge Waveform**



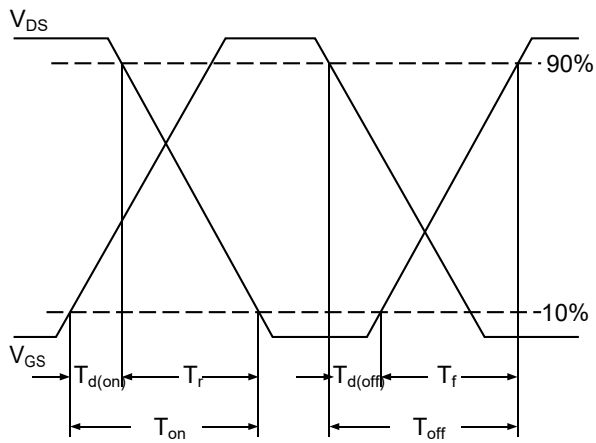
**Fig.6 Capacitance Characteristics**



**Fig.7 Normalized Transient Impedance**

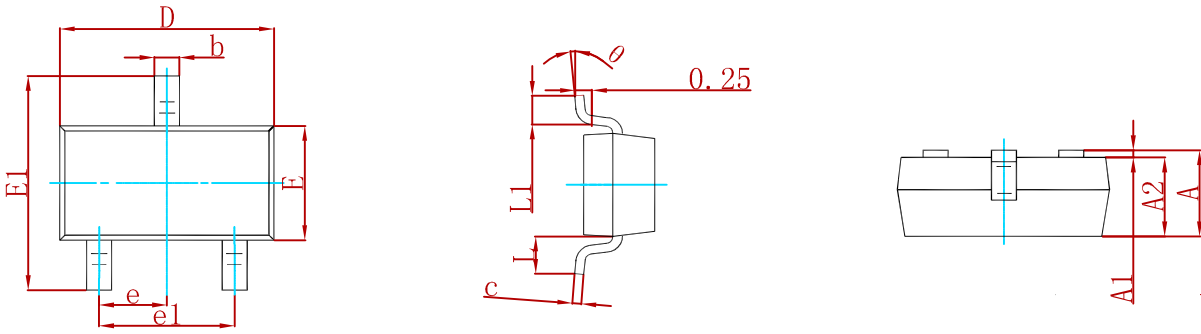


**Fig.8 Maximum Safe Operation Area**



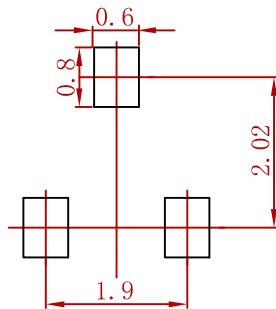
**Fig.9 Switching Time Waveform**

**PACKAGE MECHANICAL DATA**



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 0.900                     | 1.150 | 0.035                | 0.045 |
| A1     | 0.000                     | 0.100 | 0.000                | 0.004 |
| A2     | 0.900                     | 1.050 | 0.035                | 0.041 |
| b      | 0.300                     | 0.500 | 0.012                | 0.020 |
| c      | 0.080                     | 0.150 | 0.003                | 0.006 |
| D      | 2.800                     | 3.000 | 0.110                | 0.118 |
| E      | 1.200                     | 1.400 | 0.047                | 0.055 |
| E1     | 2.250                     | 2.550 | 0.089                | 0.100 |
| e      | 0.950 TYP                 |       | 0.037 TYP            |       |
| e1     | 1.800                     | 2.000 | 0.071                | 0.079 |
| L      | 0.550 REF                 |       | 0.022 REF            |       |
| L1     | 0.300                     | 0.500 | 0.012                | 0.020 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |

**Suggested Pad Layout**



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance: ± 0.05mm.
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

| P/N     | PKG    | QTY  |
|---------|--------|------|
| FDV301N | SOT-23 | 3000 |

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